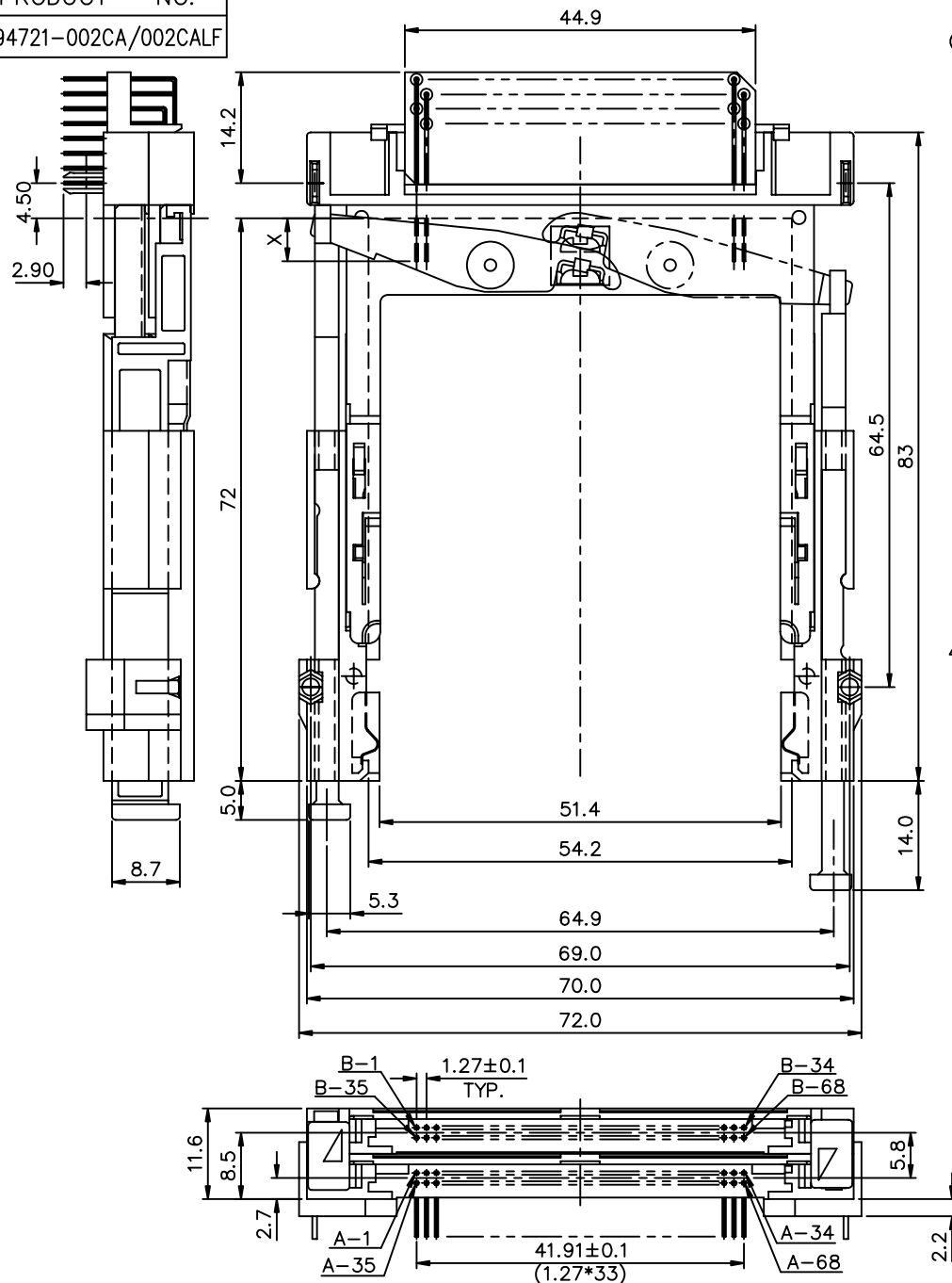


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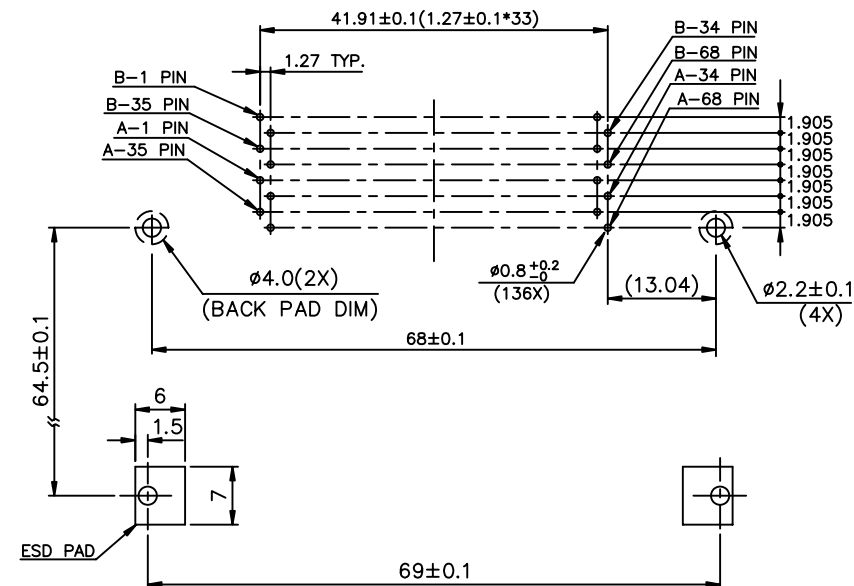
PRODUCT NO.
94721-002CA/002CALF



NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
 - TO MOUNT PART ① ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART ② WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART ① (HEADER ASS'Y)
PLASTIC : HOUSING ...LCP UL94V-0 BLACK
LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK
PIN : PHOSPHOR BRONZE
 - PART ② (EJECT MECHANISM ASS'Y)
PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK
: PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
SOLDER TAIL : 2.5µm MIN. Sn-Pb
: 2.5µm MIN. PURE Sn (FOR -*****LF)
- DIM "X"

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68
- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



mat'l code				tolerance unless otherwise specified		CUSTOMER COPY		A FCI		www.fciconnect.com	
rev.	ecn	no.	dr	date	linear	0. ± 0.50	projection	title		68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3	
K						.0 ± 0.30		product family		code	
						.00 ± 0.15		size		dwg no.	
					angles	± 2°		A3		94721	
					dr	C L FENG	04/06/94	unit		mm/inch	
					enr	JOSEPH HSIA	04/06/94	scale		1:5:1	
					chr	JOSEPH HSIA	04/06/94	sheet		2 OF	
					appd	D K WANG	04/06/94	sheet		2 OF	
sheet	revision										
index	sheet										

PDM: Rev:K

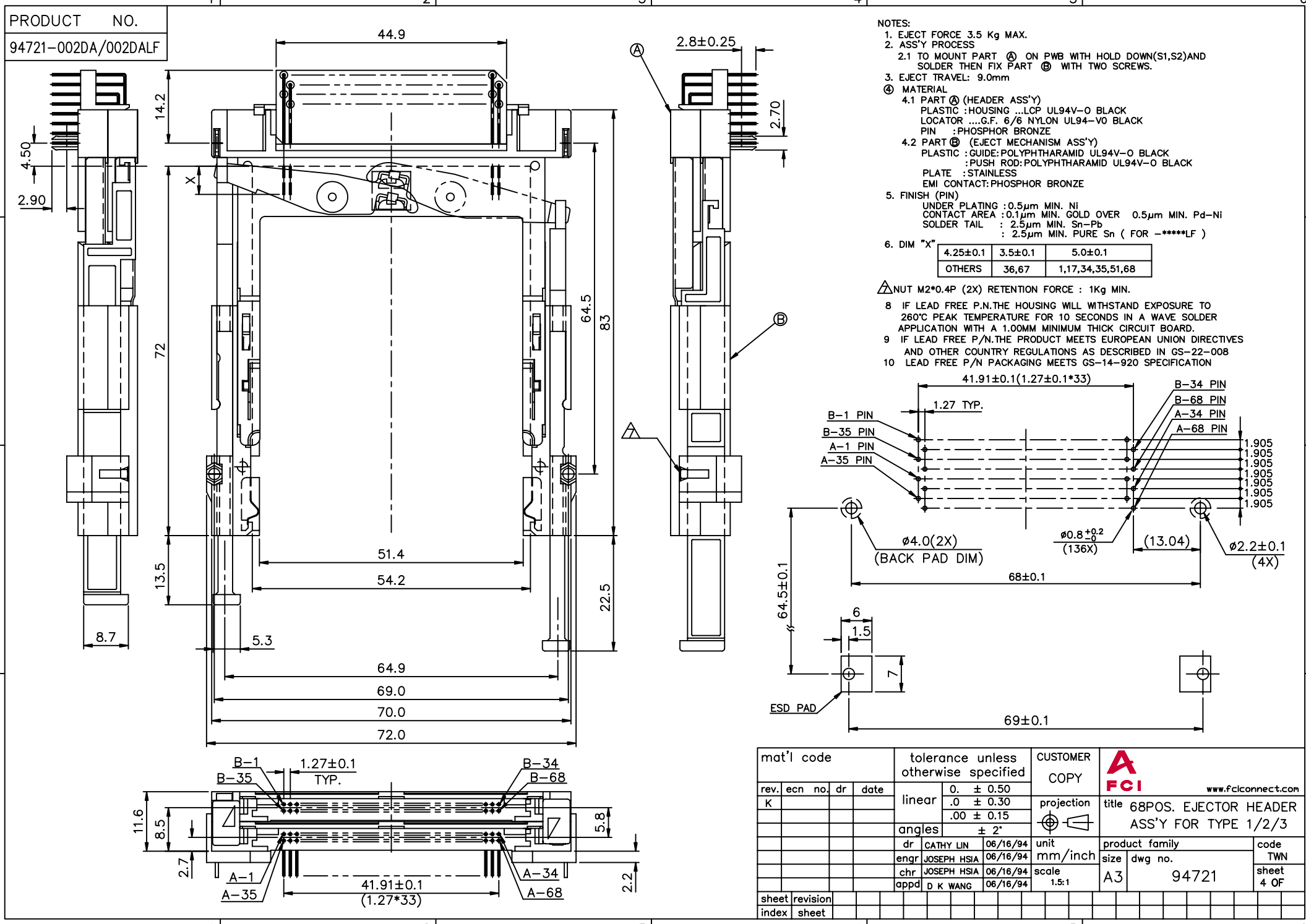
STATUS: Released

Printed: May 06, 2009

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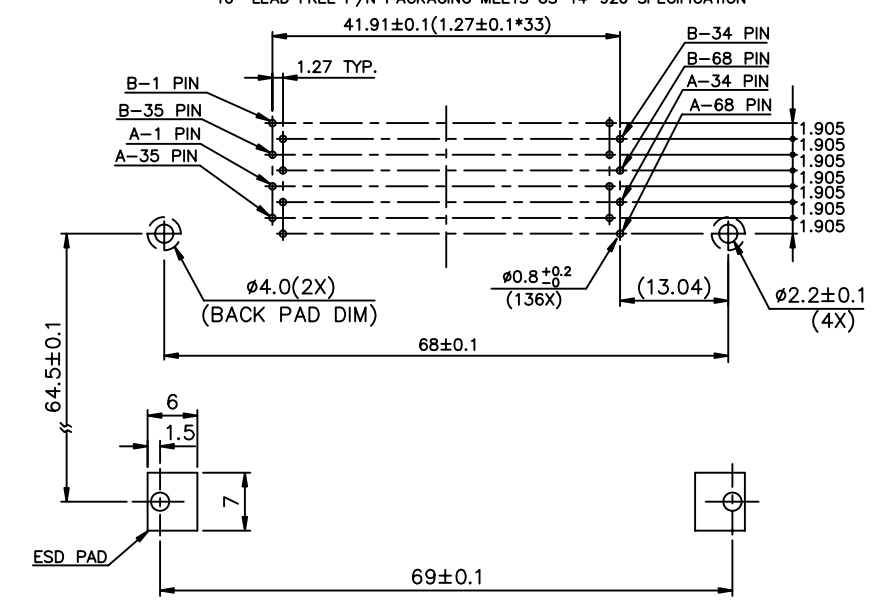
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
- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
 - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART (A) (HEADER ASS'Y)
PLASTIC : HOUSING ...LCP UL94V-0 BLACK
LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK
PIN : PHOSPHOR BRONZE
 - PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK
PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
SOLDER TAIL : 2.5µm MIN. Sn-Pb
: 2.5µm MIN. PURE Sn (FOR -****LF)
- DIM "X"

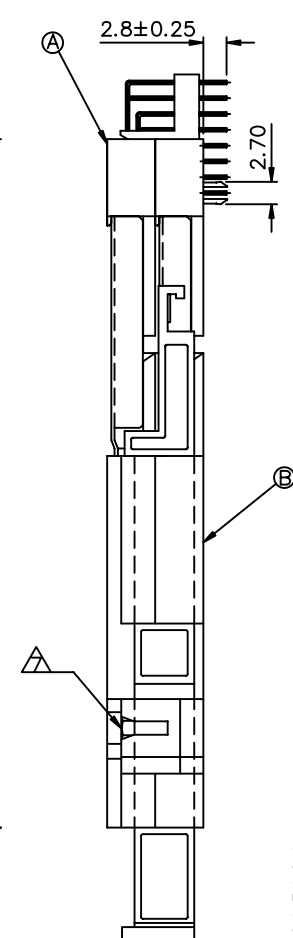
4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

△ NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.

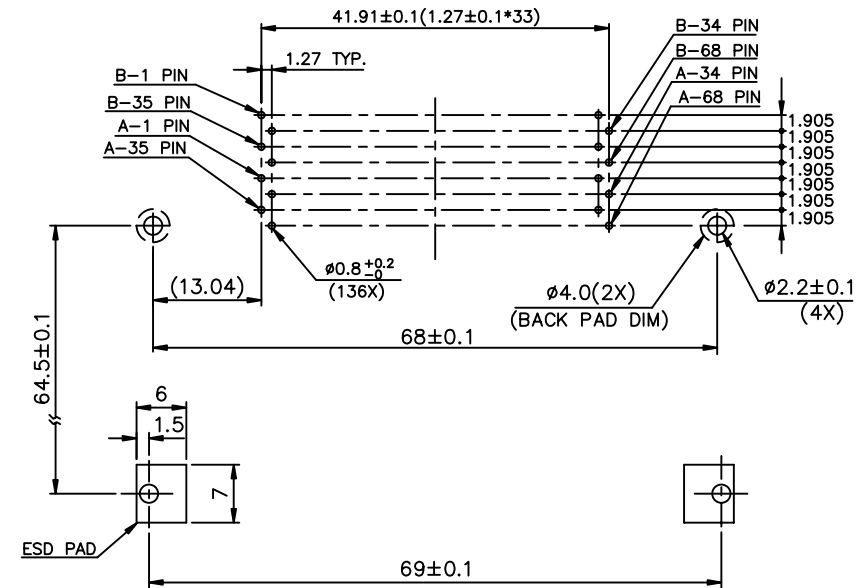
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION





mat'l code					tolerance unless otherwise specified			CUSTOMER COPY		<div><div>A</div><div>FCI</div></div> <div>www.fciconnect.com</div>	
rev.	ecn	no.	dr	date	linear	0. ± 0.50		projection 	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3		
K						.0 ± 0.30					
						.00 ± 0.15					
					angles	± 2°					
					dr	CATHY LIN	06/16/94	unit	product family		code
					enrg	JOSEPH HSIA	06/16/94	mm/inch	size dwg no.		TWN
					chr	JOSEPH HSIA	06/16/94	scale	A3 94721		sheet 4 OF
					appd	D K WANG	06/16/94	1.5:1			
sheet	revision										
index	sheet										



- ANUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



mat'l code					tolerance unless otherwise specified			CUSTOMER COPY		<div> www.fciconnect.com</div>		
rev.	ecn	no.	dr	date	linear	0. ± 0.50		projection 	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3			
K						.0 ± 0.30						
						.00 ± 0.15						
					angles	± 2°						
					dr	C L FENG	10/07/94	unit	product family		code	
					engr	JOSEPH HSIA	10/07/94	mm/inch			TWN	
					chr	JOSEPH HSIA	10/07/94	scale	size dwg no.		sheet	
					appd	D K WANG	10/07/94	1:1	A3 94721		6 OF	
sheet	revision											
index	sheet											

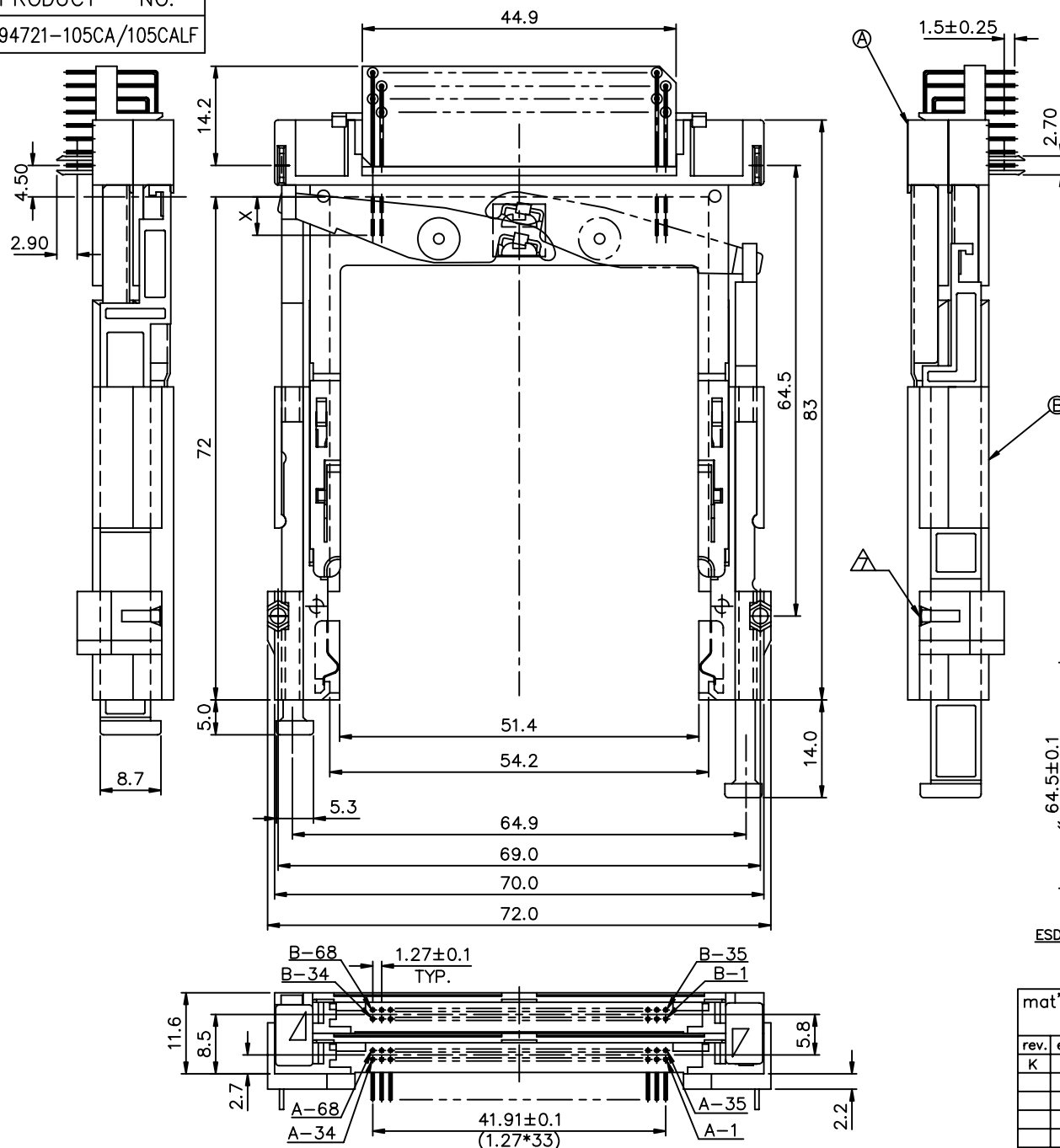
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D

PRODUCT	NO.
94721-105CA/105CALF	



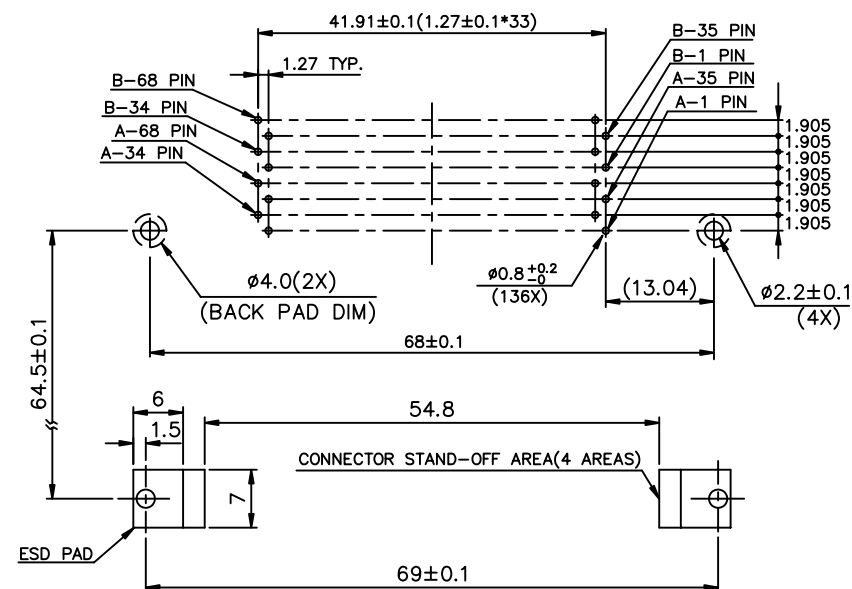
NOTES:

1. EJECT FORCE: 3.5 Kg MAX.
2. ASS'Y PROCESS
2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2) AND
SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
(4) MATERIAL
4.1 PART (A) (HEADER ASS'Y)
PLASTIC : HOUSINGLCP UL94V-O BLACK
LOCATORG.F. 6/6 NYLON UL94-V0 BLACK
PIN : PHOSPHOR BRONZE
4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : GUIDE: POLYPHTHAMID UL94V-O BLACK
PUSH ROD: POLYPHTHAMID UL94V-O BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)

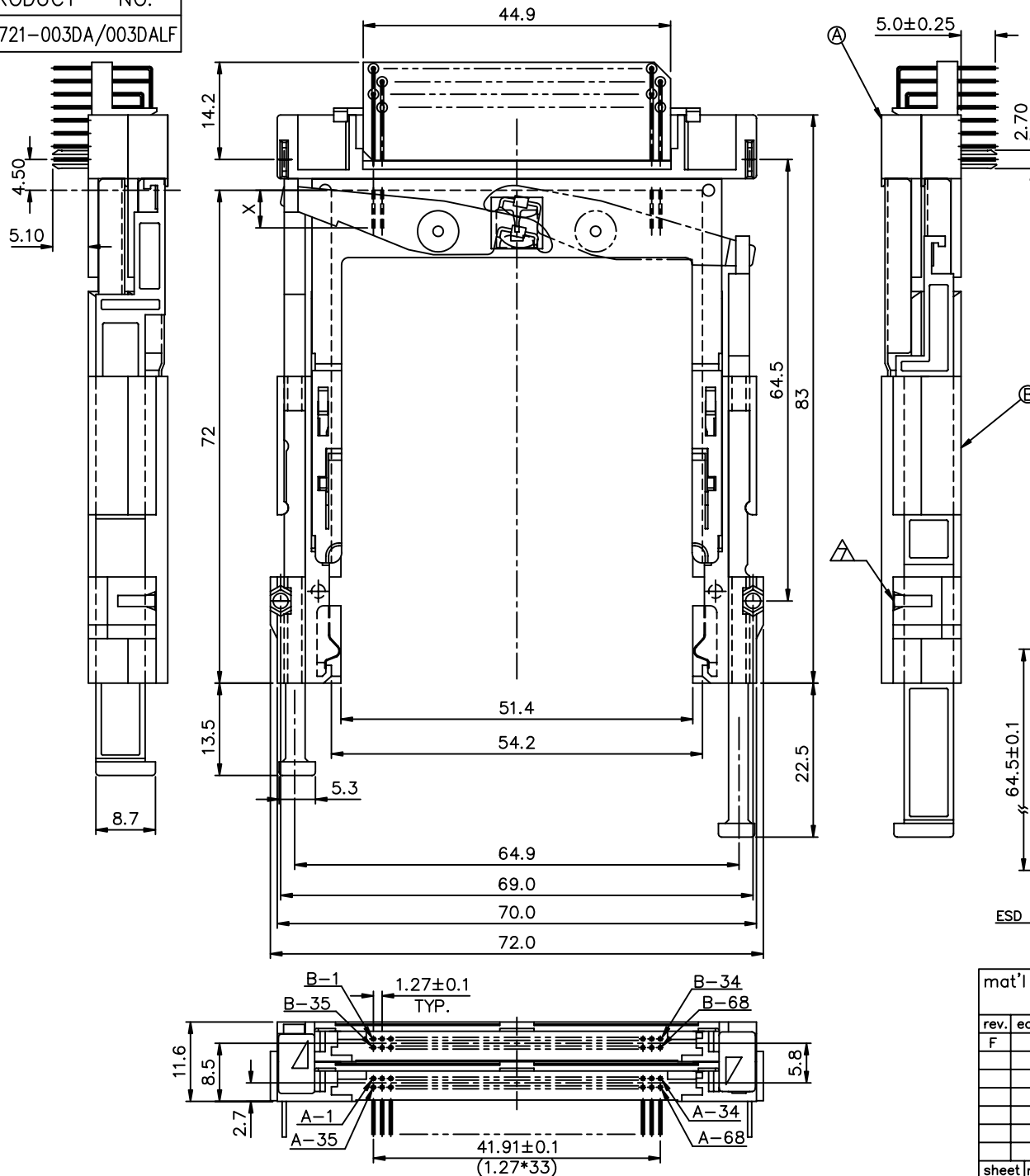
4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

△NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.

- 8 IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER
APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES
AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

[illegible]

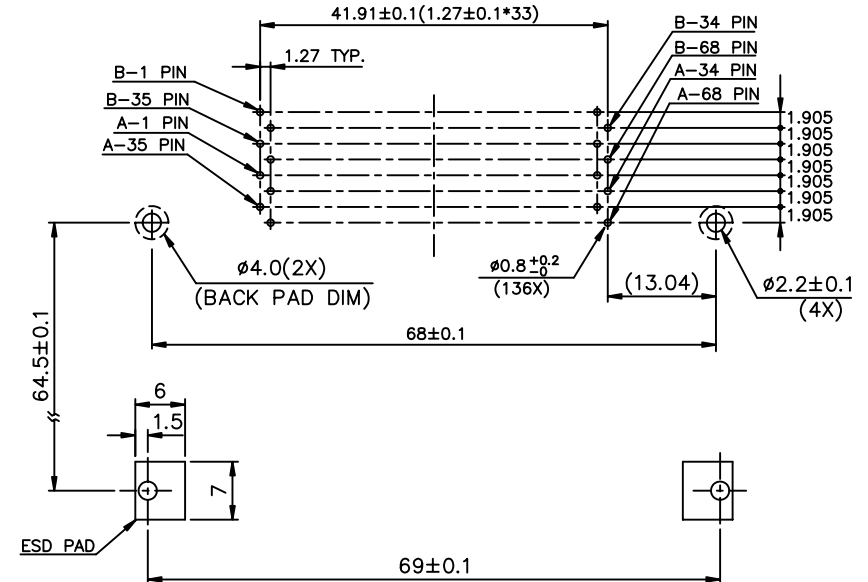
PRODUCT NO.
 94721-003DA/003DALF



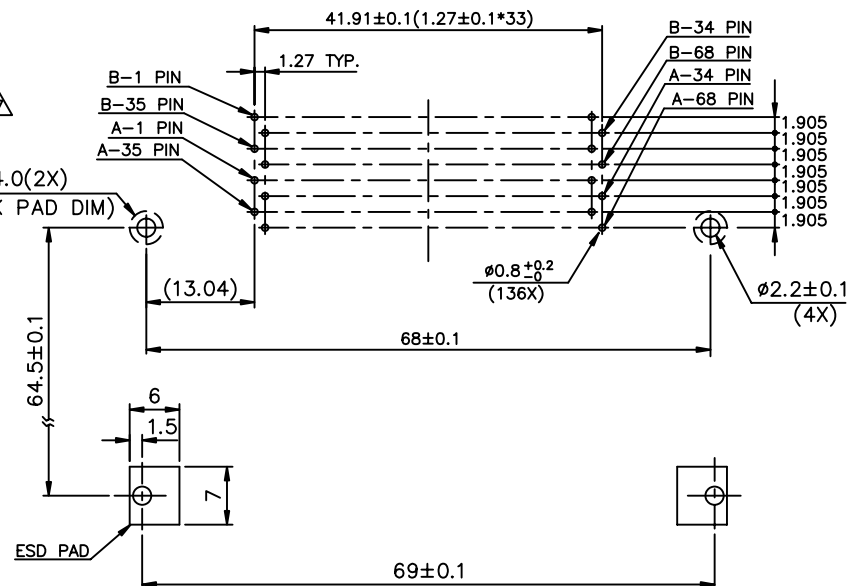
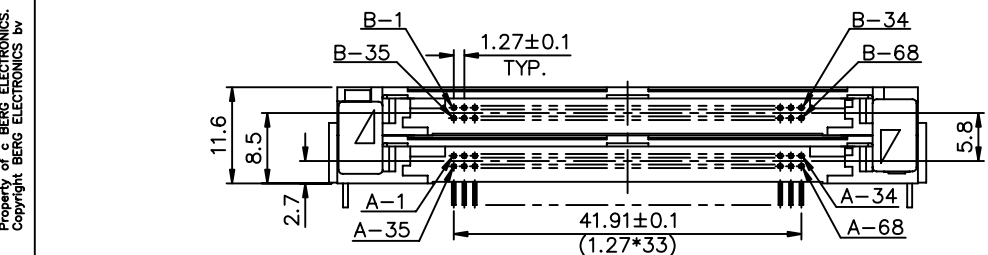
NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
 - TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2) AND SOLDER THEN FIX PART B WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART A (HEADER ASS'Y)
 - PLASTIC : HOUSING ...LCP UL94V-0 BLACK
 - LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK
 - PIN : PHOSPHOR BRONZE
 - PART B (EJECT MECHANISM ASS'Y)
 - PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK
 - PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK
 - PLATE : STAINLESS
 - EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. Ni
 - CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR *****LF)
- DIM "X"

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68
- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

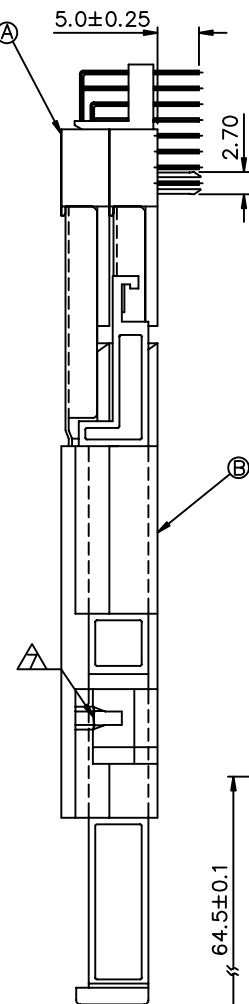


mat'l code				tolerance unless otherwise specified		CUSTOMER COPY		A FCI	
rev.	ecn	no.	dr	date	linear	0. ± 0.50	projection	www.fciconnect.com	
F						.0 ± 0.30		title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3	
						.00 ± 0.15		product family	
					angles	± 2'		code	
			dr	WENDY CHEN	03/23/95	unit	mm/inch	size	
			enr	JOSEPH HSIA	03/23/95	scale	1.5:1	dwg no.	
			chr	JOSEPH HSIA	03/23/95			A3	
			appd	D K WANG	03/23/95			94721	
sheet	revision							TWN	
index	sheet							sheet 8 OF	



- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

Printed: May 06, 2009



-
- 41.91±0.1(1.27±0.1*33)
- 1.27 TYP.
- B-1 PIN
B-35 PIN
A-1 PIN
A-35 PIN
- B-34 PIN
B-68 PIN
A-34 PIN
A-68 PIN
- 1.905
1.905
1.905
1.905
1.905
1.905
1.905
- 64.5±0.1
- φ4.0(2X)
(BACK PAD DIM)
- φ0.8^{+0.2}₋₀
(136X)
- (13.04)
- φ2.2±0.1
(4X)
- 68±0.1
- 6
1.5
7
- ESD PAD
- 69±0.1

Printed: May 06, 2009

